Statements of Support for UCIe 1.1 Specification

Alibaba
"It's thrilling to witness the introduction of new features, like automotive enhancement and full-stack streaming protocol, in UCIe 1.1. These enhancements are expected to further broaden the applications of UCIe and fuel the rapid growth of the chiplet ecosystem. Alibaba Cloud is proud to be part of this journey."
Dr. Jian Chen, Chief Architect of Cloud Server Infrastructure, Alibaba Cloud

AMD
"The UCIe 1.1 specification, which adds new features to optimize silicon and packaging costs, additional protocol flexibility and automotive use cases, takes the first step towards establishing a chiplet ecosystem. We are proud of the UCIe Consortium's progress so far and look forward to establishing a truly pervasive universal chiplet ecosystem."
Nathan Kalyanasundharam, Corporate Fellow and AMD Infinity Fabric Lead Architect, AMD

Arm
"As compute requirements continue to grow and evolve across all industries, we must deliver scalable, cost-effective solutions and new approaches. Arm partners are already delivering chiplet-based solutions in infrastructure applications; in automotive, chiplets can reduce time to market, allow for new performance points and enable unique SoC designs in applications such as ADAS and infotainment, while still delivering the dedicated features tailored to the safety and real-time needs of the market. Arm will continue to work with industry leaders in the UCIe Consortium on standards and specifications like the UCIe 1.1 Specification as the Consortium expand to increase interoperability and address industry needs."
Andy Rose, VP Technology Strategy and Fellow, Arm

Astera Labs
"Chiplets will play a significant role in enabling accelerated computing for AI infrastructure and requires a robust interoperable chiplet ecosystem. The UCIe 1.1 Specification is a big step on the road to interoperability, providing critical enhancements to support more usage models and compliance testing. Astera Labs' is proud to support this broad industry effort and work with our partners and customers to expand our roadmap of connectivity solutions."
Jitendra Mohan, CEO, Astera Labs

Blue Cheetah Analog Design
"UCIe has gained industry-wide attention and highlighted the tremendous interest in an open chiplet economy. The UCIe 1.1 Specification includes many important clarifications and improvements, bringing the industry closer to this goal. As the chiplet landscape progresses, Blue Cheetah will continue to enable customers to adopt the chiplet paradigm through its customized die-to-die interface solutions, including support for UCIe."
Elad Alon, CEO, Blue Cheetah Analog Design

Eliyan
"Eliyan is proud to be contributing and sharing our expertise in high-speed and power-efficient interconnect to the further evolution of the UCIe standard. The Consortium has put together an effective framework that will advance us further toward the goal of an open chiplet ecosystem and Version 1.1 of the spec includes many critical features. As a provider of a fully UCIe compatible solution that has the flexibility to achieve even higher speeds and lower power, Eliyan looks forward to supporting and contributing to this die-to-die protocol."
Patrick Soheili, Co-founder, Director and Vice President of Strategy and Business at Eliyan

GM
"GM is incredibly excited to see the ratification and release of UCIe Spec 1.1 and the official formation of a dedicated Automotive Working Group to bring forward and address the growing needs of Automotive compute. The rate at which we see compute growing in the Automotive space – given the rate of adoption of ADAS and advanced IVI – has highlighted the need for advanced packaging and safe/reliable Die-to-Die interconnect. We look forward to engaging with partners across the industry through UCIe to bring and grow the automotive chiplet ecosystem."
Bassam Ziadeh, Global Technical Specialist – Advanced Packaging, GM

Hyundai
"I am delighted to extend my enthusiastic endorsement for the UCIe specification 1.1 release. The formation of the Automotive Working Group and the incorporation of automotive-specific requirements UCIe 1.1's ECNs showcase the industry's commitment to advancing chiplet technology for automotive applications, promising enhanced performance and adaptability in multi-die systems for our vehicles. I look forward to the continued collaboration with UCIe in driving innovation and efficiency in the automotive semiconductor ecosystem."
Jongsun Kim, VP, Semiconductor Development Group, IATD, Hyundai Motor Group

Imec
"With the release of UCIe™ Specification 1.1, new Engineering Change Notices (ECNs), and the formation of the UCIe Consortium Automotive Working Group, we excitedly anticipate the rapid adoption of chiplets within the automotive industry.""
Bart Plackle, VP Automotive, Imec

Intel
"Intel is proud to be a founding member of the UCIe consortium. Chiplets are continuing to become a critical technology for the semiconductor industry. Intel Foundry Services (IFS) is focusing on UCIe to enable our foundry customers to build interoperable silicon solutions, based upon industry standards."
Bob Brennan, Vice President of Customer Enablement, Intel Foundry Services

Marvell
"Marvell believes that standardization of die-to-die interfaces will enable significant innovation and scaling of cloud-optimized silicon. We are very supportive of the latest UCIe 1.1 Specification release as it provides sufficient flexibility to enable a range of applications in the growing market for chiplet-based semiconductor designs."

Mark Kuemerle, VP Technology Compute & Custom Solutions, Marvell

Mercedes
"As the first Automotive OEM member of UCIe™, Mercedes-Benz is committed to standardizing chiplet technologies. We appreciate the UCIe consortium for providing a platform to present automotive-semiconductor requirements, resulting in the unanimous acceptance of the UCIe specification V1.1. We are dedicated to revolutionizing the automotive computing landscape with the goal of increasing road safety and giving customers back time spent on the road."
Markus Schäfer, Member of the Board of Management of Mercedes-Benz Group AG, Chief Technology Officer

proteanTecs
"The UCIe 1.1 specification is a pivotal milestone toward building an open chiplet ecosystem and is a testament to the invaluable work done by UCIe Consortium members. proteanTecs is pleased to see new lane monitoring capabilities included, which will improve the visibility of the link's performance and health. Interconnect monitoring is crucial for the adoption of the UCIe standard in mission-critical applications, such as automotive, and will make compliance testing more accurate and transparent."
Nir Sever, Sr. Director of Business Development, proteansTecs

Socionext Inc.
"Socionext strives to provide optimum silicon solutions to customers who seek innovations in the global marketplace. As Moore's law slows down, the industry is facing new challenges that include enhancing data traffic in high-performance computing, balancing requirements for computing performance and footprint, as well as heterogeneous integration of high-speed I/O and high-speed computing devices. The UCIe standard plays a key role in addressing these challenges. In particular, the UCIe 1.1 Specification has enhanced features for functional safety, and we expect its adoption will be accelerated in the automotive domain, one of our primary focus areas."
Hisato Yoshida, Corporate Executive Vice President and Head of Global Business Development, Socionext

Samsung
"As Moore's Law slows down, the semiconductor industry is facing many new challenges and limitations. The Samsung AVP Team is excited to tackle heterogeneous integration and advanced packaging, which will help overcome the limitations of Moore's law-like scaling. Heterogeneous integration will play an important role in innovations to meet the ever-increasing computing performance requirements. We are excited to be part of the successful distribution of the UCIe 1.1 Specification and as one of the co-founders of the UCIe Consortium, Samsung will continue our contribution toward developing the 3DIC, memory interconnect, automotive chiplet, and further standard enhancements."
Dr. Moonsoo Kang, Executive Vice President and Head of the Advanced Packaging Business Team, Samsung Electronics

Synopsys
"As multi-die systems revolutionize the semiconductor industry in architectural form and function, the UCIe 1.1 specification enables rapid adoption by providing reliable interoperability between heterogeneous dies on different process nodes. As an active member of the UCIe Consortium, Synopsys

helps designers get a jump start on their multi-die system designs with our complete UCIe IP and verification IP solutions, which have been adopted by multiple customers."
John Koeter, Senior Vice President of Marketing and Strategy for IP, Synopsys